

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chen-Hua Yu</td> <td>07/13/2012</td> </tr> <tr> <td>Yung Ching Chen</td> <td>07/13/2012</td> </tr> <tr> <td>Chien-Hsun Lee</td> <td>07/13/2012</td> </tr> <tr> <td>Jiun Yi Wu</td> <td>07/13/2012</td> </tr> <tr> <td>Mirng-Ji Lii</td> <td>07/13/2012</td> </tr> <tr> <td>Ming-Da Cheng</td> <td>07/13/2012</td> </tr> </tbody> </table>		Name	Execution Date	Chen-Hua Yu	07/13/2012	Yung Ching Chen	07/13/2012	Chien-Hsun Lee	07/13/2012	Jiun Yi Wu	07/13/2012	Mirng-Ji Lii	07/13/2012	Ming-Da Cheng	07/13/2012
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<table border="1"> <tr> <td>Name:</td> <td>Taiwan Semiconductor Manufacturing Company, Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Rd. 6</td> </tr> <tr> <td>Internal Address:</td> <td>Science-Based Industrial Park</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77 R.O.C.</td> </tr> </table>		Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	Street Address:	No. 8, Li-Hsin Rd. 6	Internal Address:	Science-Based Industrial Park	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77 R.O.C.		
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PROPERTY NUMBERS Total: 1															
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13552375</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13552375										
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Application Number:	13552375														
CORRESPONDENCE DATA															
Fax Number:	(972)732-9218														
Phone:	972-732-1001														
Email:	docketing@slater-matsil.com														
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>															
Correspondent Name:	Slater & Matsil, L.L.P.														
Address Line 1:	17950 Preston Road														
Address Line 2:	Suite 1000														
Address Line 4:	Dallas, TEXAS 75252														

CH \$40.00 13552375

ATTORNEY DOCKET NUMBER:	TSM12-0310
NAME OF SUBMITTER:	Kasey Edwards
Total Attachments: 2 source=TSM12-0310_Assignment#page1.tif source=TSM12-0310_Assignment#page2.tif	

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

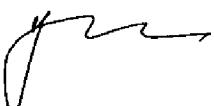

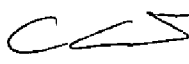
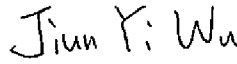
WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	<i>Package on Package Devices and Methods of Packaging Semiconductor Dies</i>			
SIGNATURE OF INVENTOR AND NAME	 Chen-Hua Yu	 Yung Ching Chen	 Chien-Hsun Lee	 Jiun Yi Wu
DATE	7/13/12	7/13/2012	7/13/12	7/13/12
RESIDENCE (City, County, State)	Hsin-Chu City Taiwan, R.O.C.	Dali City Taiwan, R.O.C.	Chu-tung Town Taiwan, R.O.C.	Zhongli City Taiwan, R.O.C.

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WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

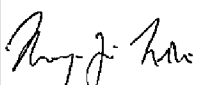
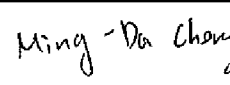
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I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

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TITLE OF INVENTION	<i>Package on Package Devices and Methods of Packaging Semiconductor Dies</i>			
SIGNATURE OF INVENTOR AND NAME	 Ming-Ji Lii	 Ming-Da Cheng		
DATE	07/13/2012	07/13/2012		
RESIDENCE (City, County, State)	Sinpu Township Taiwan, R.O.C.	Jhubei City Taiwan, R.O.C.		